

E13C7C2F-120.000M TR

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REGULATORY COMPLIANCE (Data Sheet downloaded on May 13, 2018)


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ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) LVPECL (PECL) 3.3Vdc 6 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD) 120.000MHz ± 100 ppm over 0°C to +70°C

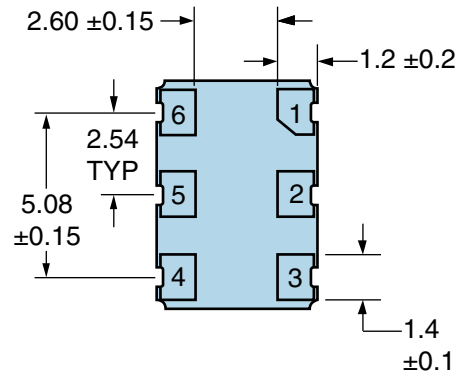
ELECTRICAL SPECIFICATIONS

Nominal Frequency	120.000MHz
Frequency Tolerance/Stability	± 100 ppm Maximum over 0°C to +70°C (Inclusive of all conditions: Calibration Tolerance (at 25°C), Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration)
Supply Voltage	3.3Vdc $\pm 5\%$
Input Current	75mA Maximum
Output Voltage Logic High (Voh)	Vdd-1.025Vdc Minimum, 2.35Vdc Typical, Vdd-0.88Vdc Maximum
Output Voltage Logic Low (Vol)	Vdd-1.81Vdc Minimum, 1.60Vdc Typical, Vdd-1.62Vdc Maximum
Rise/Fall Time	300pSec Typical, 700pSec Maximum (Measured at 20% to 80% of Waveform)
Duty Cycle	50 $\pm 5\%$ (Measured at 50% of Waveform)
Load Drive Capability	50 Ohms into Vdd-2.0Vdc
Output Logic Type	LVPECL
Phase Noise	-60dBc/Hz at 10Hz Offset, -95dBc/Hz at 100Hz Offset, -125dBc/Hz at 1kHz Offset, -143dBc/Hz at 10kHz Offset, -145dBc/Hz at 100kHz Offset, -145dBc/Hz at 1MHz Offset, -146dBc/Hz at 10MHz Offset (All Values are Typical)
Logic Control / Additional Output	Tri-State and Complementary Output
Tri-State Input Voltage (Vih and Vil)	Vih of 70% of Vdd Minimum or No Connect to Enable Output and Complementary Output, Vil of 30% of Vdd Maximum to Disable High Impedance Output and Complementary Output
Standby Current	30 μ A Maximum (Without Load)
RMS Phase Jitter	0.4pSec Typical, 1pSec Maximum (Fj=12kHz to 20MHz; Random)
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

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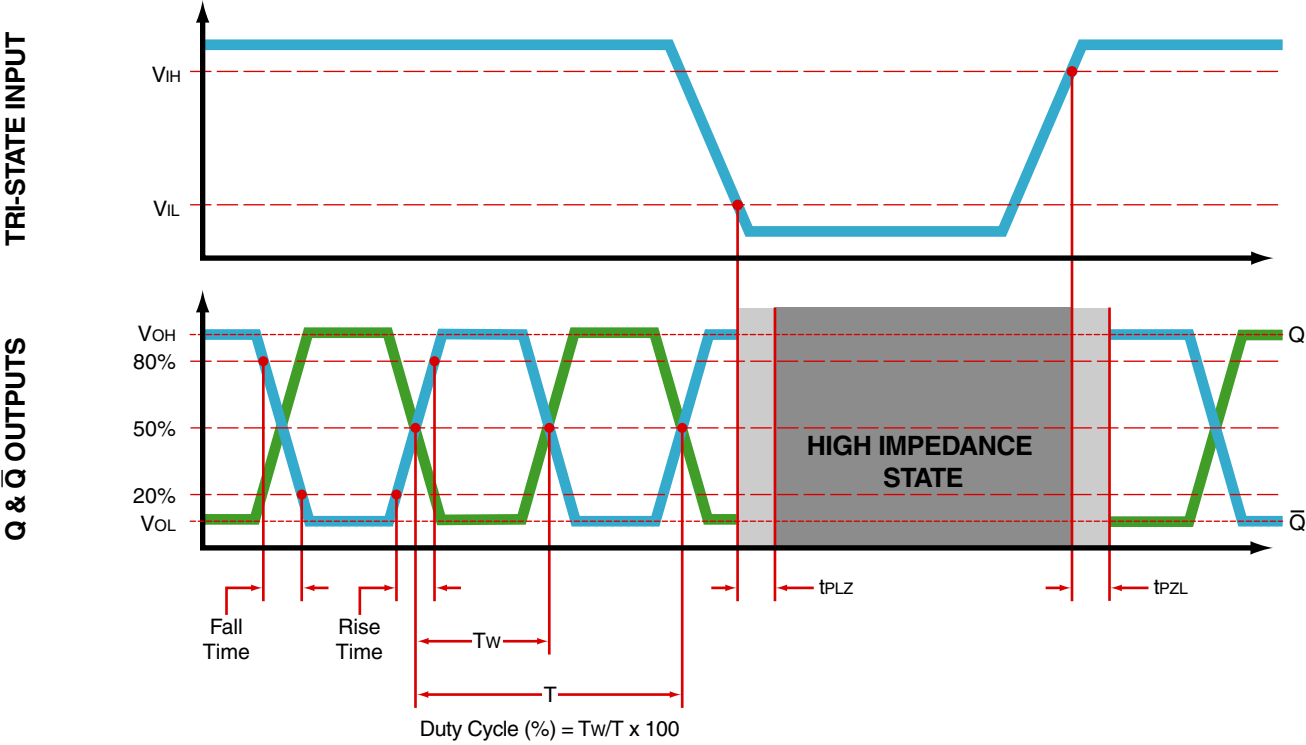
LINE	MARKING
1	ECLIPTEK
2	120.00M
3	XXXXXX XXXXXX=Ecliptek Manufacturing Identifier

Figure 1: Dimensions of the test board. The diagram shows a 3x2 grid of blue square components. Dimensions are given in inches with multipliers in parentheses. Horizontal dimensions: 1.80 (X6) between columns, 2.39 (X3) from left edge to first column, and 2.00 (X6) from second column to right edge. Vertical dimensions: 0.54 (X4) from top edge to first row, 2.00 (X6) between rows, and 2.39 (X3) from third row to bottom edge. A label 'Solder Land (X6)' points to the bottom-right component.

1-800-ECLIPTEK or 714.433.1200

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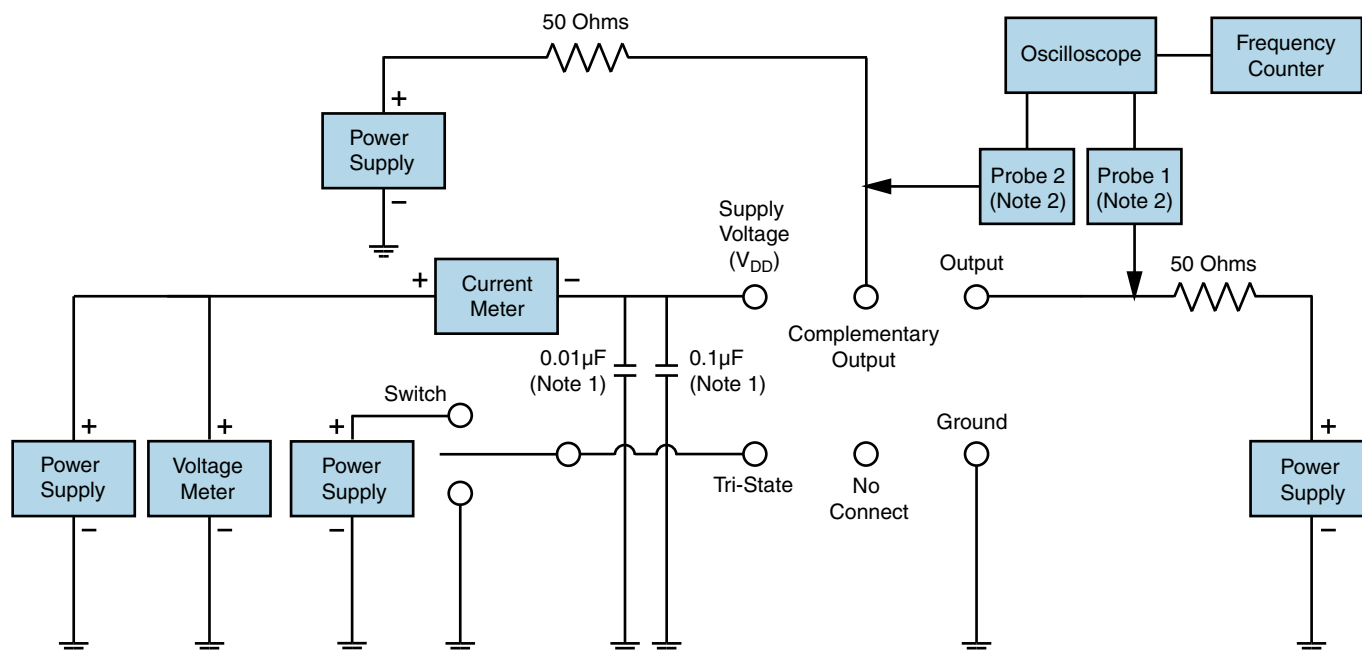
OUTPUT WAVEFORM & TIMING DIAGRAM



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Test Circuit for Tri-State and Complementary Output



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>500MHz) passive probe is recommended.

Note 3: Test circuit PCB traces need to be designed for a characteristic line impedance of 50 ohms.

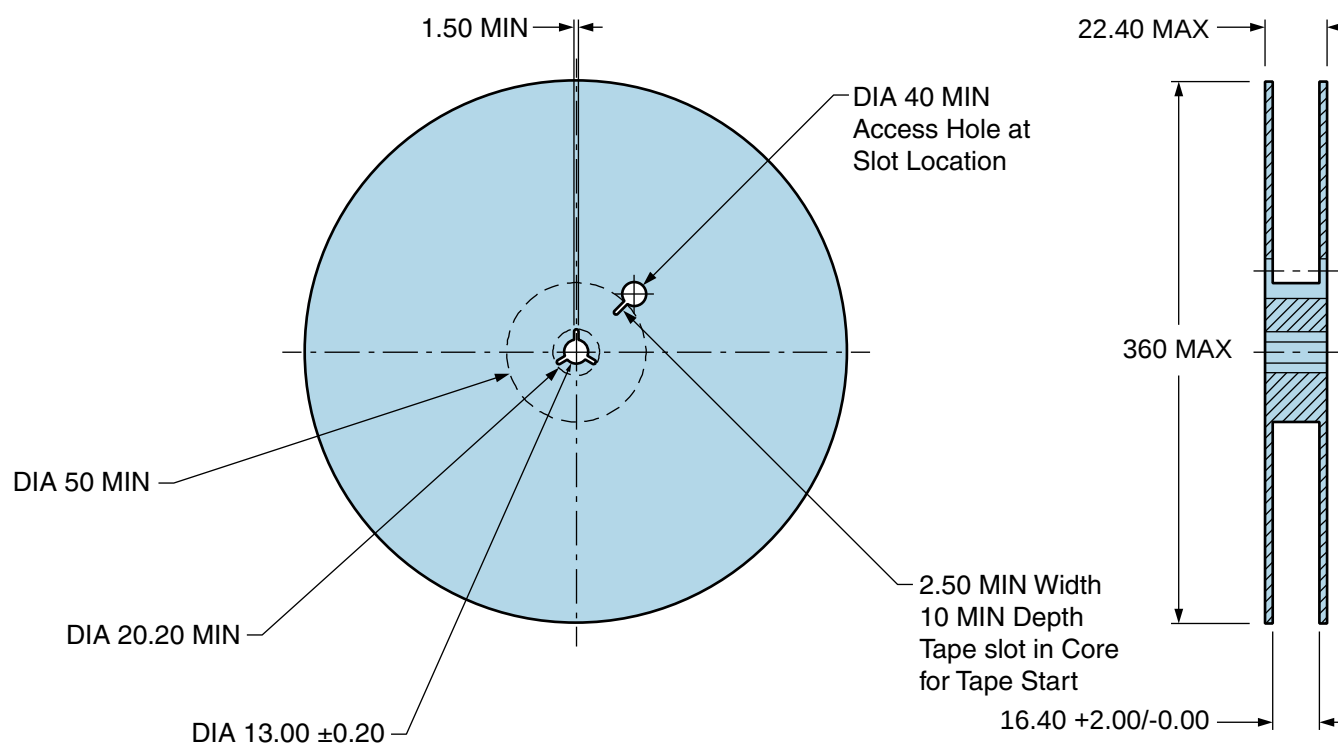
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Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

All Dimensions in Millimeters

Compliant to EIA-481



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Recommended Solder Reflow Methods



High Temperature Infrared/Convection

Ts MAX to Tl (Ramp-up Rate)	3°C/Second Maximum
Preheat	
- Temperature Minimum (Ts MIN)	150°C
- Temperature Typical (Ts TYP)	175°C
- Temperature Maximum (Ts MAX)	200°C
- Time (ts MIN)	60 - 180 Seconds
Ramp-up Rate (Tl to Tp)	3°C/Second Maximum
Time Maintained Above:	
- Temperature (Tl)	217°C
- Time (tL)	60 - 150 Seconds
Peak Temperature (Tp)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (Tp Target)	250°C +0/-5°C
Time within 5°C of actual peak (tp)	20 - 40 Seconds
Ramp-down Rate	6°C/Second Maximum
Time 25°C to Peak Temperature (t)	8 Minutes Maximum
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

Ts MAX to TL (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (Ts MIN)	N/A
- Temperature Typical (Ts TYP)	150°C
- Temperature Maximum (Ts MAX)	N/A
- Time (ts MIN)	60 - 120 Seconds
Ramp-up Rate (TL to TP)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum
Peak Temperature (TP)	240°C Maximum
Target Peak Temperature (TP Target)	240°C Maximum 2 Times / 230°C Maximum 1 Time
Time within 5°C of actual peak (tP)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)